AMENDMENTS TO THE CLAIMS

1. (Currently amended) A method of manufacturing an IC chip packaged device ~~in which~~ comprising:

transporting a film substrate that has antenna circuits formed at a fixed spacing on one surface thereof ~~is transported~~ at a constant speed, and

mounting IC chips ~~are moved~~ along the film substrate~~, and are mounted~~ , at the fixed spacing on the film substrate by one of a plurality of synchronized roller sections provided along the direction in which the film substrate is transported so as to be connected to the antenna circuits.

2. (Original) The method of manufacturing an IC chip packaged device according to claim 1, wherein an image of the IC chip is picked up, a correction amount for correcting the position where the IC chip is to be mounted is then calculated from the picked up image, and the position where the IC chip is to be mounted is then corrected.

3. (Currently amended) An apparatus for manufacturing an IC chip packaged device comprising:

a transporting section that transports a film substrate that has antenna circuits formed at a fixed spacing on one surface thereof at a constant speed; and

an IC chip mounting section that mounts IC chips on the film substrate,

wherein the IC chip mounting section is provided with: a synchronized roller section that, while moving the IC chips along the film substrate, mounts the IC chips at the fixed spacing on the film substrate that is being transported at the constant speed; and an IC chip supply section that supplies the IC chips to the synchronized roller section, and

the IC chip mounting section is provided with a plurality of the synchronized roller sections along the direction in which the film substrate is transported by the transporting section.

4. Cancelled.

5. (Original) The apparatus for manufacturing an IC chip packaged device according to claim 3, wherein, of the plurality of synchronized roller sections, at least one is a dedicated backup synchronized roller section that mounts an IC chip on the antenna circuit where an IC chip has not been mounted by the other synchronized roller sections.

6. (Currently amended) An apparatus for manufacturing an IC chip packaged device comprising:

a transporting section that transports a film substrate; and

an IC chip mounting section that mounts IC chips on the film substrate,

wherein the transporting section has a surface supporting section that supports on its surface the film substrate from a position in front of a mounting position where the IC chip is mounted by the IC chip mounting section to a position behind the mounting position, ~~and~~

the IC chip mounting section has a synchronized roller section that, while moving the IC chips at the same speed as the film substrate, mounts the IC chips on the film substrate, and an IC chip supply section that supplies the IC chips to the synchronized roller section,

the surface supporting section has an arc shape protruding toward the IC chip mounting section.

7. (Original) The apparatus for manufacturing an IC chip packaged device according to claim 6, wherein the surface supporting section has a suction mechanism that suctions the film substrate.

8. (Currently amended) An apparatus for manufacturing an IC chip packaged device comprising:

a transporting section that transports a film substrate; and

an IC chip mounting section that mounts IC chips on the film substrate,

wherein the IC chip mounting section has a synchronized roller section that, while moving the IC chips at the same speed as the film substrate, mounts the IC chips on the film substrate, and an IC chip supply section that supplies the IC chips to the synchronized roller section, ~~and~~

the synchronized roller section is provided with a roller that axially rotates around an axis of rotation and mounts the IC chips on the film substrate, and protruding portions that hold the IC chips at a distal end portion are formed on a circumferential surface of the roller at equal intervals in the circumferential direction thereof,

the IC chip mounting section is provided with a plurality of the synchronized roller sections along the direction in which the film substrate is transported by the transporting section.

9. (New) The method of manufacturing the IC chip packaged device according to claim 1,

wherein of the plurality of synchronized roller sections, at least one is a dedicated backup synchronized roller section and

the dedicated backup synchronized roller section mounts an IC chip on the antenna circuit where an IC chip has not been mounted by the other synchronized roller sections.

10. (New) The apparatus for manufacturing an IC chip packaged device according to claim 6, wherein the transporting section is further provided with a pair of small rollers that are provided facing the surface supporting section sandwiching the film substrate.

11. (New) The apparatus for manufacturing an IC chip packaged device according to claim 8,, wherein of the plurality of synchronized roller sections at last one is a dedicated backup synchronized roller section that mounts an IC chip on the antenna circuit where an IC chip has not been mounted by the other synchronized roller sections.

12. (New) The apparatus for manufacturing an IC chip packaged device according to claim 8,

wherein the axis of rotation of the roller of the synchronized roller section is kept in a state parallel to the transported film substrate and vertical to the direction where the film substrate is transported, and

the synchronized roller section mounts IC chips on the film substrate without moving up and down.

13. (New) The apparatus for manufacturing an IC chip packaged device according to claim 8, wherein as a result of an index movement the IC chip supply section supplies the IC chips to the synchronized roller section in a state where the synchronized roller section chips, and the synchronized roller section mounts IC chips on the film substrate in a state where the roller of the synchronized roller section rotates.

14, (New) The method as claimed in claim 1 wherein the synchronized roller sections are disposed on a common circumferential surface.